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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	18MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	26
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 3.6V
Data Converters	A/D 8x8b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	28-TSSOP
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/p89lpc9331fdh-512

2.2 Additional features

- A high performance 80C51 CPU provides instruction cycle times of 111 ns to 222 ns for all instructions except multiply and divide when executing at 18 MHz. This is six times the performance of the standard 80C51 running at the same clock frequency. A lower clock frequency for the same performance results in power savings and reduced EMI.
- Serial flash In-Circuit Programming (ICP) allows simple production coding with commercial EPROM programmers. Flash security bits prevent reading of sensitive application programs.
- Serial flash In-System Programming (ISP) allows coding while the device is mounted in the end application.
- In-Application Programming (IAP) of the flash code memory. This allows changing the code in a running application.
- Watchdog timer with separate on-chip oscillator, nominal 400 kHz, calibrated to ±5 %, requiring no external components. The watchdog prescaler is selectable from eight values.
- High-accuracy internal RC oscillator option, with clock doubler option, allows operation without external oscillator components. The RC oscillator option is selectable and fine tunable.
- Clock switching on the fly among internal RC oscillator, watchdog oscillator, external clock source provides optimal support of minimal power active mode with fast switching to maximum performance.
- Idle and two different power-down reduced power modes. Improved wake-up from Power-down mode (a LOW interrupt input starts execution). Typical power-down current is 1 μA (total power-down with voltage comparators disabled).
- Active-LOW reset. On-chip power-on reset allows operation without external reset components. A software reset function is also available.
- Configurable on-chip oscillator with frequency range options selected by user programmed flash configuration bits. Oscillator options support frequencies from 20 kHz to the maximum operating frequency of 18 MHz.
- Oscillator fail detect. The watchdog timer has a separate fully on-chip oscillator allowing it to perform an oscillator fail detect function.
- Programmable port output configuration options: quasi-bidirectional, open drain, push-pull, input-only.
- High current sourcing/sinking (20 mA) on eight I/O pins (P0.3 to P0.7, P1.4, P1.6, P1.7). All other port pins have high sinking capability (20 mA). A maximum limit is specified for the entire chip.
- Port ‘input pattern match’ detect. Port 0 may generate an interrupt when the value of the pins match or do not match a programmable pattern.
- Controlled slew rate port outputs to reduce EMI. Outputs have approximately 10 ns minimum ramp times.
- Only power and ground connections are required to operate the P89LPC9331/9341/9351/9361 when internal reset option is selected.
- Four interrupt priority levels.
- Eight keypad interrupt inputs, plus two additional external interrupt inputs.
- Schmitt trigger port inputs.
- Second data pointer.
- Emulation support.

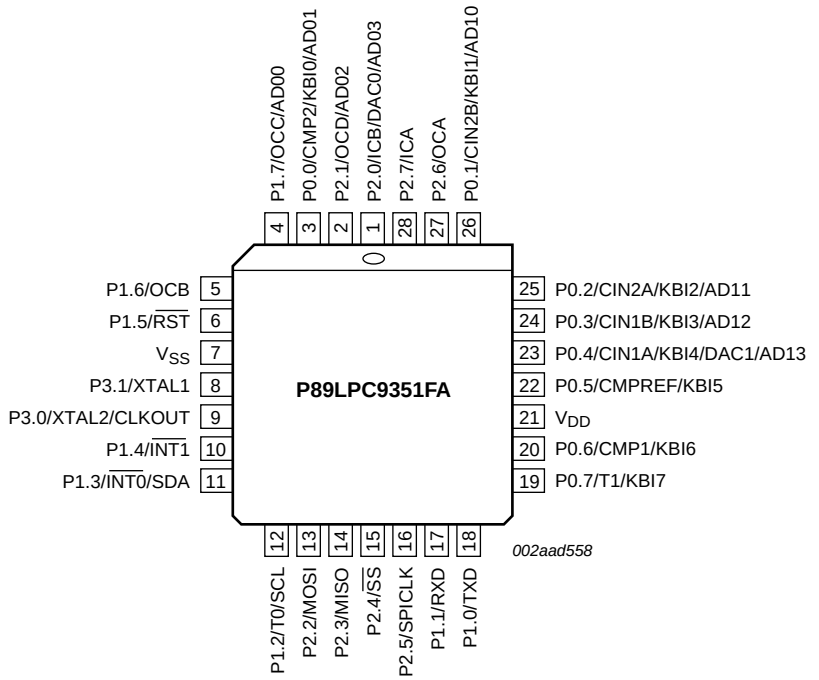


Fig 6. P89LPC9351 PLCC28 pin configuration

Table 3. Pin description *…continued*

Symbol	Pin	Type	Description
	PLCC28, TSSOP28		
P3.1/XTAL1	8	I/O	**P3.1 —** Port 3 bit 1.
		I	**XTAL1 —** Input to the oscillator circuit and internal clock generator circuits (when selected via the flash configuration). It can be a port pin if internal RC oscillator or watchdog oscillator is used as the CPU clock source, **and** if XTAL1/XTAL2 are not used to generate the clock for the RTC/system timer.
V_{SS}	7	I	**Ground:** 0 V reference.
V_{DD}	21	I	**Power supply:** This is the power supply voltage for normal operation as well as Idle and Power-down modes.

[1] Input/output for P1.0 to P1.4, P1.6, P1.7. Input for P1.5.

Table 4. Special function registers - P89LPC9331/9341 *…continued*

** indicates SFRs that are bit addressable.*

Name	Description	SFR addr.	Bit functions and addresses								Reset value	
			MSB							LSB	Hex	Binary
SBUF	Serial Port data buffer register	99H									xx	xxxx xxxx
	Bit address		**9F**	**9E**	**9D**	**9C**	**9B**	**9A**	**99**	**98**		
SCON*	Serial port control	98H	SM0/FE	SM1	SM2	REN	TB8	RB8	TI	RI	00	0000 0000
SSTAT	Serial port extended status register	BAH	DBMOD	INTLO	CIDIS	DBISEL	FE	BR	OE	STINT	00	0000 0000
SP	Stack pointer	81H									07	0000 0111
SPCTL	SPI control register	E2H	SSIG	SPEN	DORD	MSTR	CPOL	CPHA	SPR1	SPR0	04	0000 0100
SPSTAT	SPI status register	E1H	SPIF	WCOL	-	-	-	-	-	-	00	00xx xxxx
SPDAT	SPI data register	E3H									00	0000 0000
TAMOD	Timer 0 and 1 auxiliary mode	8FH	-	-	-	T1M2	-	-	-	T0M2	00	xxx0 xxx0
	Bit address		**8F**	**8E**	**8D**	**8C**	**8B**	**8A**	**89**	**88**		
TCON*	Timer 0 and 1 control	88H	TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0	00	0000 0000
TH0	Timer 0 high	8CH									00	0000 0000
TH1	Timer 1 high	8DH									00	0000 0000
TL0	Timer 0 low	8AH									00	0000 0000
TL1	Timer 1 low	8BH									00	0000 0000
TMOD	Timer 0 and 1 mode	89H	T1GATE	T1C/T	T1M1	T1M0	T0GATE	T0C/T	T0M1	T0M0	00	0000 0000
TRIM	Internal oscillator trim register	96H	RCCLK	ENCLK	TRIM.5	TRIM.4	TRIM.3	TRIM.2	TRIM.1	TRIM.0	[5][6]	
WDCON	Watchdog control register	A7H	PRE2	PRE1	PRE0	-	-	WDRUN	WDTOF	WDCLK	[4][6]	

Table 6. Special function registers - P89LPC9351/9361

** indicates SFRs that are bit addressable.*

Name	Description	SFR addr.	Bit functions and addresses								Reset value	
			MSB							LSB	Hex	Binary
		Bit address	E7	E6	E5	E4	E3	E2	E1	E0		
ACC*	Accumulator	E0H									00	0000 0000
ADCON0	A/D control register 0	8EH	ENBI0	ENADCI0	TMM0	EDGE0	ADCI0	ENADC0	ADCS01	ADCS00	00	0000 0000
ADCON1	A/D control register 1	97H	ENBI1	ENADCI1	TMM1	EDGE1	ADCI1	ENADC1	ADCS11	ADCS10	00	0000 0000
ADINS	A/D input select	A3H	ADI13	ADI12	ADI11	ADI10	ADI03	ADI02	ADI01	ADI00	00	0000 0000
ADMODA	A/D mode register A	C0H	BNDI1	BURST1	SCC1	SCAN1	BNDI0	BURST0	SCC0	SCAN0	00	0000 0000
ADMODB	A/D mode register B	A1H	CLK2	CLK1	CLK0	INBND0	ENDAC1	ENDAC0	BSA1	BSA0	00	000x 0000
AD0BH	A/D_0 boundary high register	BBH									FF	1111 1111
AD0BL	A/D_0 boundary low register	A6H									00	0000 0000
AD0DAT0	A/D_0 data register 0	C5H									00	0000 0000
AD0DAT1	A/D_0 data register 1	C6H									00	0000 0000
AD0DAT2	A/D_0 data register 2	C7H									00	0000 0000
AD0DAT3	A/D_0 data register 3	F4H									00	0000 0000
AD1BH	A/D_1 boundary high register	C4H									FF	1111 1111
AD1BL	A/D_1 boundary low register	BCH									00	0000 0000
AD1DAT0	A/D_1 data register 0	D5H									00	0000 0000
AD1DAT1	A/D_1 data register 1	D6H									00	0000 0000
AD1DAT2	A/D_1 data register 2	D7H									00	0000 0000

7.2 Enhanced CPU

The P89LPC9331/9341/9351/9361 uses an enhanced 80C51 CPU which runs at six times the speed of standard 80C51 devices. A machine cycle consists of two CPU clock cycles, and most instructions execute in one or two machine cycles.

7.3 Clocks

7.3.1 Clock definitions

The P89LPC9331/9341/9351/9361 device has several internal clocks as defined below:

OSCCLK — Input to the DIVM clock divider. OSCCLK is selected from one of four clock sources (see Figure 7) and can also be optionally divided to a slower frequency (see Section 7.11 “CCLK modification: DIVM register”).

Remark: f_{osc} is defined as the OSCCLK frequency.

CCLK — CPU clock; output of the clock divider. There are two CCLK cycles per machine cycle, and most instructions are executed in one to two machine cycles (two or four CCLK cycles).

RCCLK — The internal 7.373 MHz RC oscillator output. The clock doubler option, when enabled, provides an output frequency of 14.746 MHz.

PCLK — Clock for the various peripheral devices and is $^{CCLK}/_{2}$.

7.3.2 CPU clock (OSCCLK)

The P89LPC9331/9341/9351/9361 provides several user-selectable oscillator options in generating the CPU clock. This allows optimization for a range of needs from high precision to lowest possible cost. These options are configured when the flash is programmed and include an on-chip watchdog oscillator, an on-chip RC oscillator, an oscillator using an external crystal, or an external clock source.

7.4 Crystal oscillator option

The crystal oscillator option can be optimized for low, medium, or high frequency crystals covering a range from 20 kHz to 18 MHz. It can be the clock source of OSCCLK, and RTC. Low speed oscillator option can be the clock source of WDT.

7.4.1 Low speed oscillator option

This option supports an external crystal in the range of 20 kHz to 100 kHz. Ceramic resonators are also supported in this configuration.

7.4.2 Medium speed oscillator option

This option supports an external crystal in the range of 100 kHz to 4 MHz. Ceramic resonators are also supported in this configuration.

7.4.3 High speed oscillator option

This option supports an external crystal in the range of 4 MHz to 18 MHz. Ceramic resonators are also supported in this configuration.

Some chip functions continue to operate and draw power during Power-down mode, increasing the total power used during power-down. These include: Brownout detect, watchdog timer, comparators (note that comparators can be powered down separately), and RTC/system timer. The internal RC oscillator is disabled unless both the RC oscillator has been selected as the system clock and the RTC is enabled.

7.18.3 Total Power-down mode

This is the same as Power-down mode except that the brownout detection circuitry and the voltage comparators are also disabled to conserve additional power. The internal RC oscillator is disabled unless both the RC oscillator has been selected as the system clock **and** the RTC is enabled. If the internal RC oscillator is used to clock the RTC during power-down, there will be high power consumption. Please use an external low frequency clock to achieve low power with the RTC running during power-down.

7.19 Reset

The P1.5/$\overline{\text{RST}}$ pin can function as either a LOW-active reset input or as a digital input, P1.5. The Reset Pin Enable (RPE) bit in UCFG1, when set to logic 1, enables the external reset input function on P1.5. When cleared, P1.5 may be used as an input pin.

Remark: During a power-up sequence, the RPE selection is overridden and this pin always functions as a reset input. **An external circuit connected to this pin should not hold this pin LOW during a power-on sequence as this will keep the device in reset.** After power-up this pin will function as defined by the RPE bit. Only a power-up reset will temporarily override the selection defined by RPE bit. Other sources of reset will not override the RPE bit. When this pin functions as a reset input, an internal pull-up resistance is connected (see Table 12 “Static characteristics”).

Note: During a power cycle, V_{DD} must fall below V_{POR} before power is reapplied, in order to ensure a power-on reset (see Table 12 “Static characteristics”).

Reset can be triggered from the following sources:

- External reset pin (during power-up or if user configured via UCFG1)
- Power-on detect
- Brownout detect
- Watchdog timer
- Software reset
- UART break character detect reset

For every reset source, there is a flag in the Reset Register, RSTSRC. The user can read this register to determine the most recent reset source. These flag bits can be cleared in software by writing a logic 0 to the corresponding bit. More than one flag bit may be set:

- During a power-on reset, both POF and BOF are set but the other flag bits are cleared.
- A Watchdog reset is similar to a power-on reset, both POF and BOF are set but the other flag bits are cleared.
- For any other reset, previously set flag bits that have not been cleared will remain set.

7.19.1 Reset vector

Following reset, the P89LPC9331/9341/9351/9361 will fetch instructions from either address 0000H or the Boot address. The Boot address is formed by using the boot vector as the high byte of the address and the low byte of the address = 00H.

The boot address will be used if a UART break reset occurs, or the non-volatile boot status bit (BOOTSTAT.0) = 1, or the device is forced into ISP mode during power-on (see *P89LPC9331/9341/9351/9361 User manual*). Otherwise, instructions will be fetched from address 0000H.

7.20 Timers/counters 0 and 1

The P89LPC9331/9341/9351/9361 has two general purpose counter/timers which are upward compatible with the standard 80C51 Timer 0 and Timer 1. Both can be configured to operate either as timers or event counters. An option to automatically toggle the T0 and/or T1 pins upon timer overflow has been added.

In the ‘Timer’ function, the register is incremented every machine cycle.

In the ‘Counter’ function, the register is incremented in response to a 1-to-0 transition at its corresponding external input pin, T0 or T1. In this function, the external input is sampled once during every machine cycle.

Timer 0 and Timer 1 have five operating modes (Modes 0, 1, 2, 3 and 6). Modes 0, 1, 2 and 6 are the same for both Timers/Counters. Mode 3 is different.

7.20.1 Mode 0

Putting either Timer into Mode 0 makes it look like an 8048 Timer, which is an 8-bit Counter with a divide-by-32 prescaler. In this mode, the Timer register is configured as a 13-bit register. Mode 0 operation is the same for Timer 0 and Timer 1.

7.20.2 Mode 1

Mode 1 is the same as Mode 0, except that all 16 bits of the timer register are used.

7.20.3 Mode 2

Mode 2 configures the Timer register as an 8-bit Counter with automatic reload. Mode 2 operation is the same for Timer 0 and Timer 1.

7.20.4 Mode 3

When Timer 1 is in Mode 3 it is stopped. Timer 0 in Mode 3 forms two separate 8-bit counters and is provided for applications that require an extra 8-bit timer. When Timer 1 is in Mode 3 it can still be used by the serial port as a baud rate generator.

7.20.5 Mode 6

In this mode, the corresponding timer can be changed to a PWM with a full period of 256 timer clocks.

7.20.6 Timer overflow toggle output

Timers 0 and 1 can be configured to automatically toggle a port output whenever a timer overflow occurs. The same device pins that are used for the T0 and T1 count inputs are also used for the timer toggle outputs. The port outputs will be a logic 1 prior to the first timer overflow when this mode is turned on.

7.21 RTC/system timer

The P89LPC9331/9341/9351/9361 has a simple RTC that allows a user to continue running an accurate timer while the rest of the device is powered down. The RTC can be a wake-up or an interrupt source. The RTC is a 23-bit down counter comprised of a 7-bit prescaler and a 16-bit loadable down counter. When it reaches all logic 0s, the counter will be reloaded again and the RTCF flag will be set. The clock source for this counter can be either the CPU clock (CCLK) or the XTAL oscillator. Only power-on reset and watchdog reset will reset the RTC and its associated SFRs to the default state.

The 16-bit loadable counter portion of the RTC is readable by reading the RTCDATL and RTCDATH registers.

7.22 CCU (P89LPC9351/9361)

This unit features:

- A 16-bit timer with 16-bit reload on overflow.
- Selectable clock, with prescaler to divide clock source by any integral number between 1 and 1024.
- Four compare/PWM outputs with selectable polarity
- Symmetrical/asymmetrical PWM selection
- Two capture inputs with event counter and digital noise rejection filter
- Seven interrupts with common interrupt vector (one overflow, two capture, four compare)
- Safe 16-bit read/write via shadow registers.

7.22.1 CCU clock

The CCU runs on the CCUCLK, which is either PCLK in basic timer mode, or the output of a PLL. The PLL is designed to use a clock source between 0.5 MHz to 1 MHz that is multiplied by 32 to produce a CCUCLK between 16 MHz and 32 MHz in PWM mode (asymmetrical or symmetrical). The PLL contains a 4-bit divider to help divide PCLK into a frequency between 0.5 MHz and 1 MHz.

7.22.2 CCUCLK prescaling

This CCUCLK can further be divided down by a prescaler. The prescaler is implemented as a 10-bit free-running counter with programmable reload at overflow.

7.22.3 Basic timer operation

The timer is a free-running up/down counter with a direction control bit. If the timer counting direction is changed while the counter is running, the count sequence will be reversed. The timer can be written or read at any time.

When a reload occurs, the CCU Timer Overflow Interrupt Flag will be set, and an interrupt generated if enabled. The 16-bit CCU timer may also be used as an 8-bit up/down timer.

7.22.4 Output compare

There are four output compare channels: A, B, C and D. Each output compare channel needs to be enabled in order to operate and the user will have to set the associated I/O pin to the desired output mode to connect the pin. When the contents of the timer matches that of a capture compare control register, the Timer Output Compare Interrupt Flag (TOCFx) becomes set. An interrupt will occur if enabled.

7.22.5 Input capture

Input capture is always enabled. Each time a capture event occurs on one of the two input capture pins, the contents of the timer is transferred to the corresponding 16-bit input capture register. The capture event can be programmed to be either rising or falling edge triggered. A simple noise filter can be enabled on the input capture by enabling the Input Capture Noise Filter bit. If set, the capture logic needs to see four consecutive samples of the same value in order to recognize an edge as a capture event. An event counter can be set to delay a capture by a number of capture events.

7.22.6 PWM operation

PWM operation has two main modes, symmetrical and asymmetrical.

In asymmetrical PWM operation the CCU timer operates in down-counting mode regardless of the direction control bit.

In symmetrical mode, the timer counts up/down alternately. The main difference from basic timer operation is the operation of the compare module, which in PWM mode is used for PWM waveform generation.

As with basic timer operation, when the PWM (compare) pins are connected to the compare logic, their logic state remains unchanged. However, since bit FCO is used to hold the halt value, only a compare event can change the state of the pin.

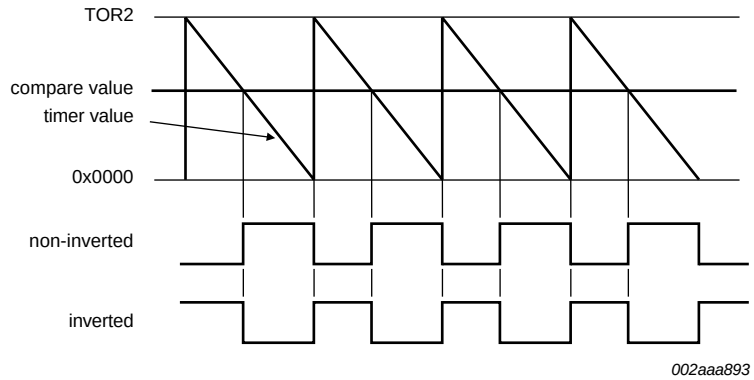


Fig 9. Asymmetrical PWM, down-counting

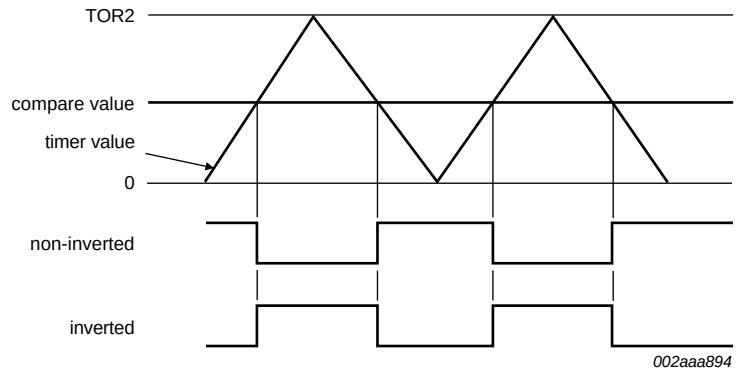


Fig 10. Symmetrical PWM

7.22.7 Alternating output mode

In asymmetrical mode, the user can set up PWM channels A/B and C/D as alternating pairs for bridge drive control. In this mode the output of these PWM channels are alternately gated on every counter cycle.

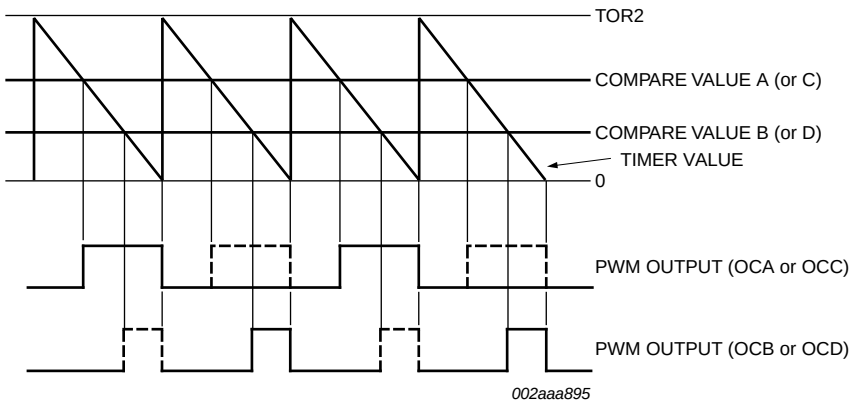


Fig 11. Alternate output mode

7.22.8 PLL operation

The PWM module features a Phase Locked Loop that can be used to generate a CCUCLK frequency between 16 MHz and 32 MHz. At this frequency the PWM module provides ultrasonic PWM frequency with 10-bit resolution provided that the crystal frequency is 1 MHz or higher. The PLL is fed an input signal from 0.5 MHz to 1 MHz and generates an output signal of 32 times the input frequency. This signal is used to clock the timer. The user will have to set a divider that scales PCLK by a factor from 1 to 16. This divider is found in the SFR register TCR21. The PLL frequency can be expressed as shown in Equation 1:

$$\text{PLL frequency} = \frac{\text{PCLK}}{(N+1)} \quad (1)$$

Where: N is the value of PLLDV3:0.

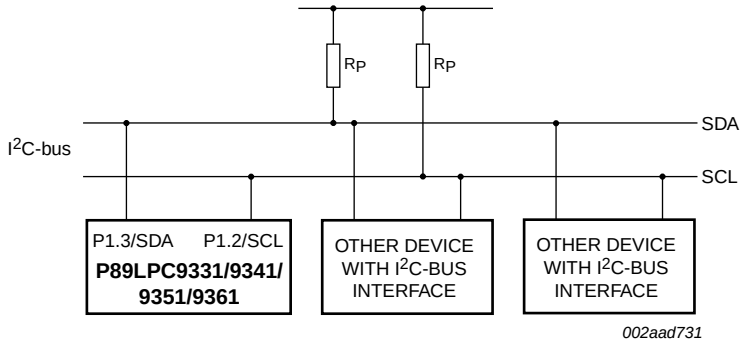


Fig 14. I^2C-bus configuration

8.3 Block diagram

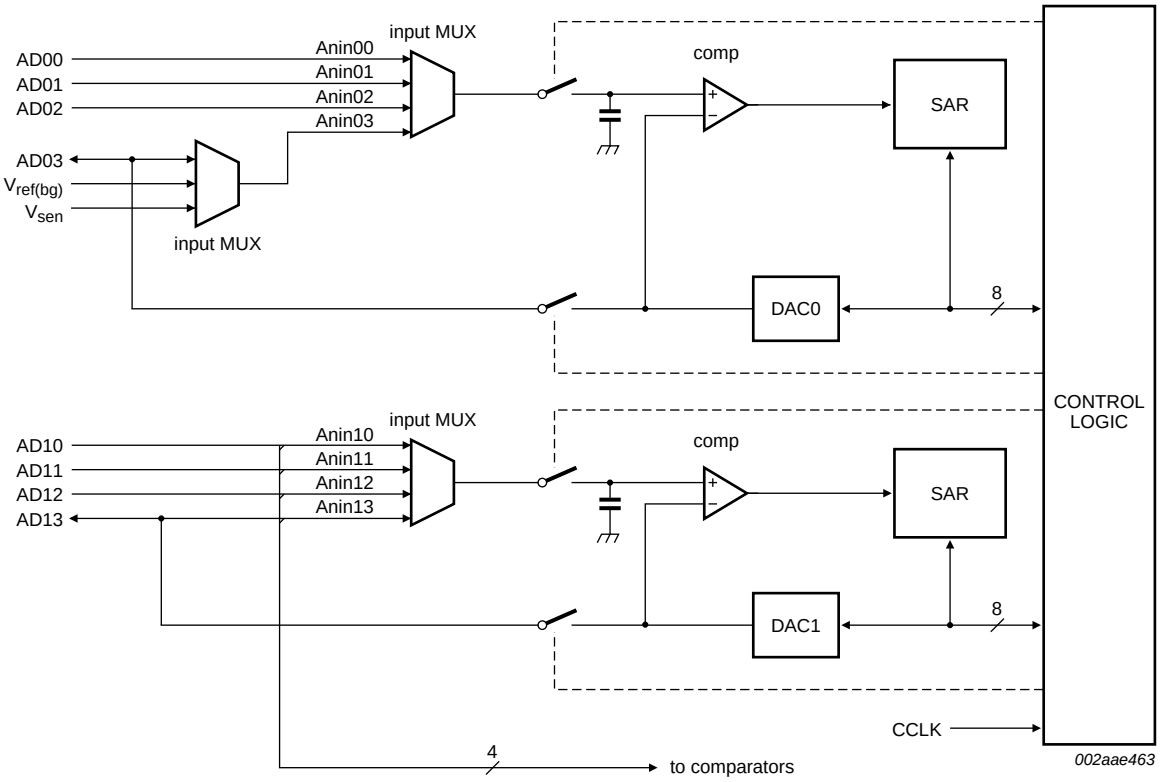


Fig 23. P89LPC9331/9341 ADC block diagram

Table 12. Static characteristics *…continued*

V_{DD} = 2.4 V to 3.6 V unless otherwise specified.
T_{amb} = −40 °C to +85 °C for industrial applications, −40 °C to +125 °C extended, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
I_{IL}	LOW-level input current	V_I = 0.4 V	[9]	-	-	−80	μA
I_{LI}	input leakage current	$V_I = V_{IL}$, V_{IH}, or $V_{th(HL)}$	[10]	-	-	±1	μA
I_{THL}	HIGH-LOW transition current	all ports; V_I = 1.5 V at V_{DD} = 3.6 V	[11]	−30	-	−450	μA
$R_{RST\_N(int)}$	internal pull-up resistance on pin $\overline{RST}$	pin $\overline{RST}$		10	-	30	kΩ
$V_{ref(bg)}$	band gap reference voltage			1.19	1.23	1.27	V
TC_{bg}	band gap temperature coefficient			-	10	20	ppm/°C

[1] Typical ratings are not guaranteed. The values listed are at room temperature, 3 V.

[2] The $I_{DD(oper)}$ specification is measured using an external clock with code while(1) {} executed from on-chip flash.

[3] The $I_{DD(idle)}$ specification is measured using an external clock with no active peripherals, with the following functions disabled: real-time clock and watchdog timer.

[4] The $I_{DD(pd)}$ specification is measured using internal RC oscillator with the following functions disabled: comparators, real-time clock, and watchdog timer.

[5] The $I_{DD(tpd)}$ specification is measured using an external clock with the following functions disabled: comparators, real-time clock, brownout detect, and watchdog timer.

[6] See Section 9 “Limiting values” for steady state (non-transient) limits on I_{OL} or I_{OH}. If I_{OL}/I_{OH} exceeds the test condition, V_{OL}/V_{OH} may exceed the related specification.

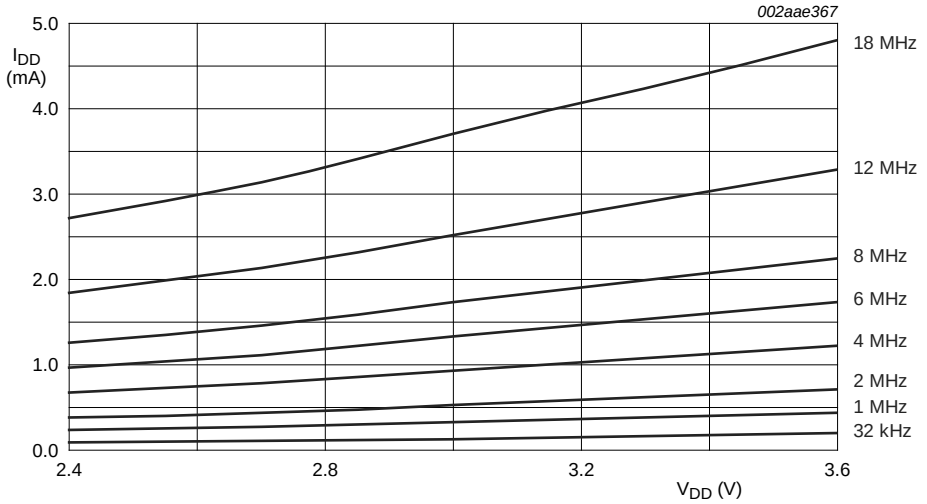
[7] This specification can be applied to pins which have A/D input or analog comparator input functions when the pin is not being used for those analog functions. When the pin is being used as an analog input pin, the maximum voltage on the pin must be limited to 4.0 V with respect to V_{SS}.

[8] Pin capacitance is characterized but not tested.

[9] Measured with port in quasi-bidirectional mode.

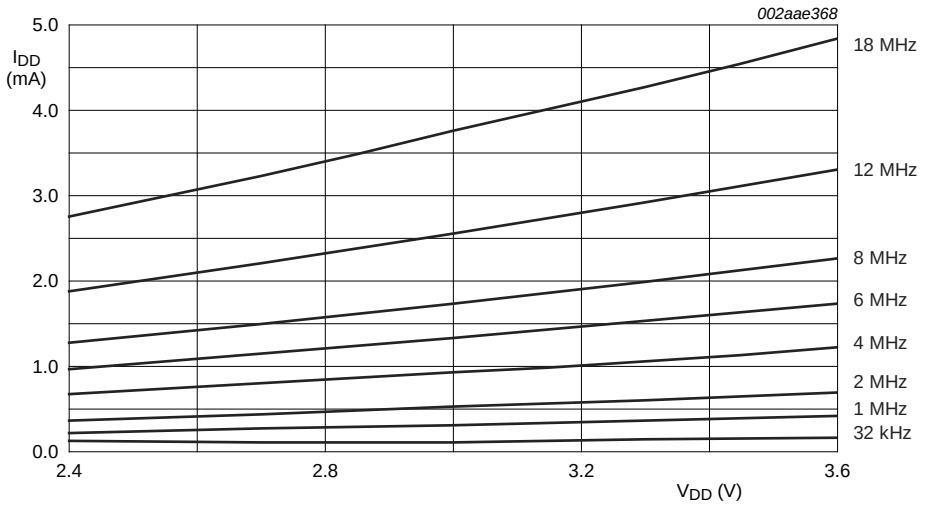
[10] Measured with port in high-impedance mode.

[11] Port pins source a transition current when used in quasi-bidirectional mode and externally driven from logic 1 to logic 0. This current is highest when V_I is approximately 2 V.



Test conditions: idle mode entered executing code from on-chip flash; using an external clock with no active peripherals, with the following functions disabled: real-time clock and watchdog timer.

Fig 30. $I_{DD(idle)}$ vs. frequency at –40 °C



Test conditions: idle mode entered executing code from on-chip flash; using an external clock with no active peripherals, with the following functions disabled: real-time clock and watchdog timer.

Fig 31. $I_{DD(idle)}$ vs. frequency at +85 °C

Table 15. Dynamic characteristics (18 MHz) *…continued*

V_{DD} = 3.0 V to 3.6 V unless otherwise specified.

T_{amb} = −40 °C to +85 °C for industrial applications, −40 °C to +125 °C extended, unless otherwise specified.[1][2]

Symbol	Parameter	Conditions	Variable clock		f_{osc} = 18 MHz		Unit
			Min	Max	Min	Max	
$t_{SPILEAD}$	SPI enable lead time	see Figure 45, 46					
	slave		250	-	250	-	ns
t_{SPILAG}	SPI enable lag time	see Figure 45, 46					
	slave		250	-	250	-	ns
$t_{SPICLKH}$	SPICLK HIGH time	see Figure 43, 44, 45, 46					
	slave		$^{3}/_{CCLK}$	-	167	-	ns
	master		$^{2}/_{CCLK}$	-	111	-	ns
$t_{SPICLKL}$	SPICLK LOW time	see Figure 43, 44, 45, 46					
	slave		$^{3}/_{CCLK}$	-	167	-	ns
	master		$^{2}/_{CCLK}$	-	111	-	ns
t_{SPIDSU}	SPI data set-up time	see Figure 43, 44, 45, 46					
	master or slave		100	-	100	-	ns
t_{SPIDH}	SPI data hold time	see Figure 43, 44, 45, 46					
	master or slave		100	-	100	-	ns
t_{SPIA}	SPI access time	see Figure 45, 46					
	slave		0	80	0	80	ns
t_{SPIDIS}	SPI disable time	see Figure 45, 46					
	slave		0	160	-	160	ns
t_{SPIDV}	SPI enable to output data valid time	see Figure 43, 44, 45, 46					
	slave		-	160	-	160	ns
	master		-	111	-	111	ns
t_{SPIOH}	SPI output data hold time	see Figure 43, 44, 45, 46	0	-	0	-	ns
t_{SPIR}	SPI rise time	see Figure 43, 44, 45, 46					
	SPI outputs (SPICLK, MOSI, MISO)		-	100	-	100	ns
	SPI inputs (SPICLK, MOSI, MISO, $\overline{SS}$)		-	2000	-	2000	ns
t_{SPIF}	SPI fall time	see Figure 43, 44, 45, 46					
	SPI outputs (SPICLK, MOSI, MISO)		-	100	-	100	ns
	SPI inputs (SPICLK, MOSI, MISO, $\overline{SS}$)		-	2000	-	2000	ns

[1] Parameters are valid over operating temperature range unless otherwise specified.

[2] Parts are tested to 2 MHz, but are guaranteed to operate down to 0 Hz.

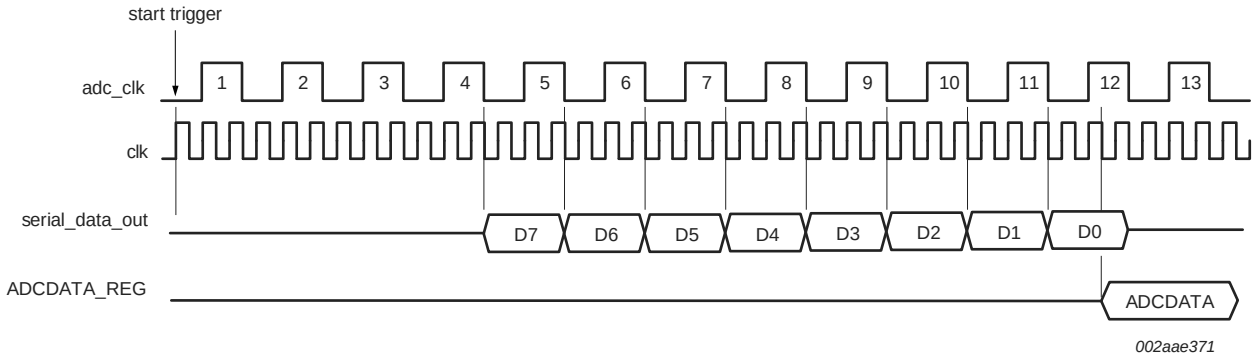
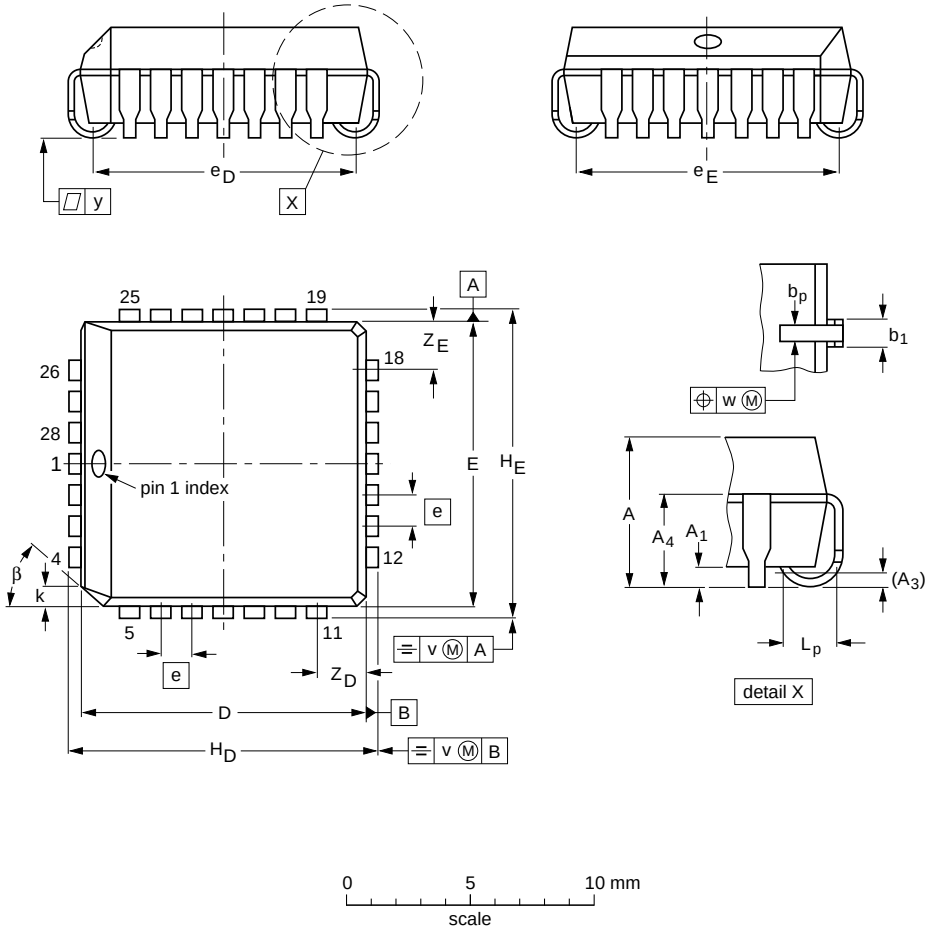


Fig 48. ADC conversion timing

13. Package outline

PLCC28: plastic leaded chip carrier; 28 leads **SOT261-2**



DIMENSIONS (mm dimensions are derived from the original inch dimensions)

UNIT	A	A_1 min.	A_3	A_4 max.	b_p	b_1	$D^{(1)}$	$E^{(1)}$	e	e_D	e_E	H_D	H_E	k	L_p	v	w	y	$Z_D^{(1)}$ max.	$Z_E^{(1)}$ max.	β
mm	4.57 4.19	0.51	0.25	3.05	0.53 0.33	0.81 0.66	11.58 11.43	11.58 11.43	1.27	10.92 9.91	10.92 9.91	12.57 12.32	12.57 12.32	1.22 1.07	1.44 1.02	0.18	0.18	0.1	2.16	2.16	45°
inches	0.180 0.165	0.02	0.01	0.12	0.021 0.013	0.032 0.026	0.456 0.450	0.456 0.450	0.05	0.43 0.39	0.43 0.39	0.495 0.485	0.495 0.485	0.048 0.042	0.057 0.040	0.007	0.007	0.004	0.085	0.085	

Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT261-2	112E08	MS-018	EDR-7319			~~99-12-27~~ 01-11-15

Fig 50. PLCC28 package outline (SOT261-2)

16. Legal information

16.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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continued >>